SPECIFICATIONS

Backlight背光源产品规格书

TOPLITC



MODEL: TBL-4546UW4

上海鼎晖科技股份有限公司

SHANGHAI TOPLITE TECHNOLOGY CO., LTD.

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1. FEATURES

- $# 43.4 \times 35.4$ mm is emitting surface size of backlight
- * Low power requirement, solid state reliability.
- * Multicolor available, stackable horizontally.
- * Categorized for luminous intensity.
- * Easy mounting on P.C. boards.
- * Remain within RoHS compliant version.

2. DESCRIPTION

[★] The TBL-4546UW4 is a 43.4 × 35.4mm

emitting surface backlight.

3. APPLICATION

- ✗ General lighting solutions
- ☆ LCD display backlight

PART NO.	SIZE	CHIP EMITTED COLOR	
TBL-4546UW4	43.4×35.4mm	White	



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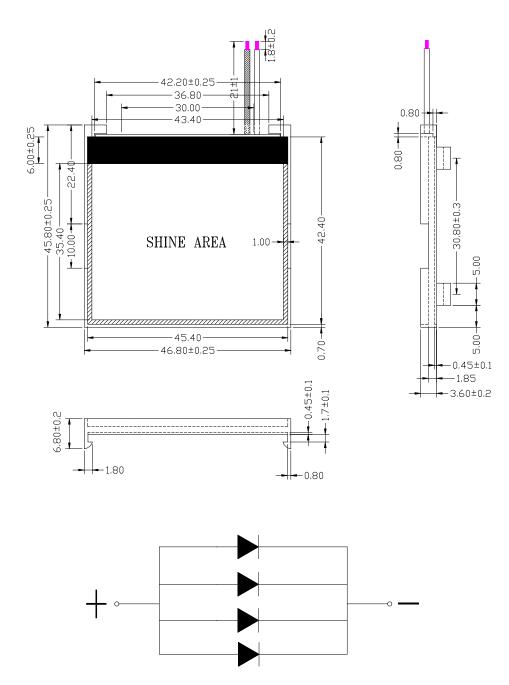
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4. PACKAGE DIMENSIONS & CIRCUIT DIAGRAM

PACKAGE

DIMENSIONS





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5. ELECTRICAL/OPTICAL CHARACTERISTIC

5-1. ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

PARAMETER	SYMBOL	VALUE	UNIT
Reverse Voltage	V _R	5	V
Peak Forward Current (1/10 Duty Cycle)	I _{PEAK}	120	mA
Power Dissipation	P _D	240	mW
Operating Temperature Range	T _A	- 35 ~ + 85	°C
Storage Temperature Range	T _{STG}	- 35 ~ + 85	°C

5-2. ELECTRICAL/OPTICAL CHARACTERISTICS (Ta=25°C)

PARAMETER	SYMBOL	MIN.	ТҮР.	MAX.	UNIT
Forward Current	If	60	70	80	mA
Forward Voltage	V _f	-	3	-	V
Peak Emission Wavelength	λp	-	-	-	nm
Spectral Line Half-Width	Δλ	-	30	-	nm
Color temperature	ТС	5000	-	8000	K
Luminous Uniformity	-	-	70%	-	-
Brightness	-	200	-	450	cd/m
Discreteness	-	-	30%	-	-



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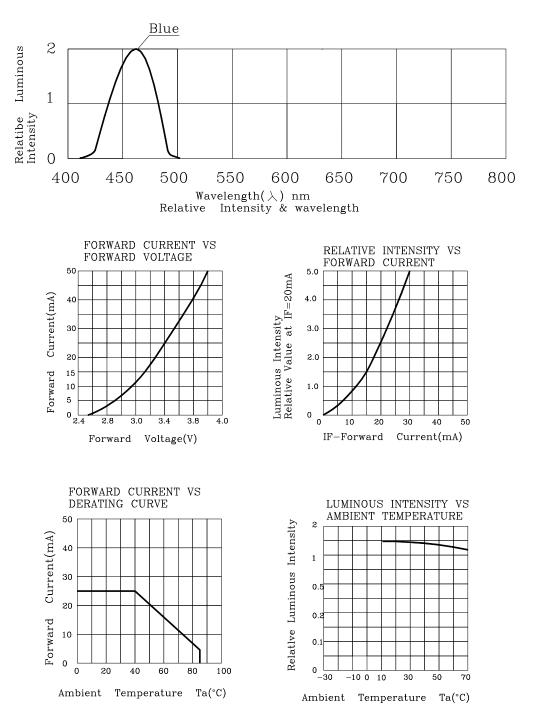
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5-3. ELECTRICAL/OPTICAL CHARACTERISTIC CURVES

ELECTRICAL/OPTICAL CHARACTERISTIC (2)





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6. QUALITY CONTROL AND ASSURANCE

CLASSIFICATION	TEST ITEM	TEST CONDITION	
ENDUTRANCE TEST	OPERATION LIFE	Ta=under room temperature If=12mA-25mA per segment or Ip=80mA/duty=1/8,Pw=1.25mS Ip=160mA/duty=1/16,Pw=1.mS(DOT) Test time=1000HRS(-24HRS+72HRS)	
	MOISTURE	Ta=65°C±5°C RH=90-95% Test time=240HRS±2HRS	
	HIGH TEMPERATURE HIGH HUMIDITY REVERSE BIAS	Ta=65°C±5°C RH=90-95% VR=5V Test time=500hrs(-24HRS+48HRS)	
	HIGH TEMPERATURE STORAGE	To evaluate device's durability for long term storage in high temperature Ta=85°C±5°C Test time=1000HRS(-24HRS+72HRS)	
	LOW TEMPERATURE STORAGE	Ta=-35°C±5°C Test time=1000HRS(-24HRS+72HRS)	
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	Ta=85°C \sim 25°C \sim -35°C time=30min 5min 30min 5min Cycle test:10cycles	
	THERMAL SHOCK	$Ta=85^{\circ}C\pm5^{\circ}C\sim-35^{\circ}C\pm5^{\circ}C time=10min\ 10min Cycle \\ test:10cycles$	
	SOLOER RESISTANCE	T.sol=260°C±5°C time=10±1sec	
	SOLOER ABILITY	T.sol=230°C±5°C time=5±1sec	



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7. SOLDERING CONDITIONS

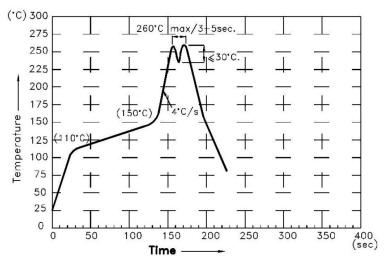
The recommended conditions for soldering are as follows.

Because the component is made with epoxy resin, the units are susceptible to heat. Therefore, the preheating and soldering temperatures should be kept as low as possible to avoid damage.

7-1. Manual Soldering Conditions(with 1.5mm Iron tip). Iron Tip Temperature: 350°C Max, Time: 3s Max.

Position: The iron should be situated at least 2mm away from the root of the leads.

7-2. Through the Wave Soldering Conditions Wave Soldering Profile For Lead-free Through-hole LED.



- 7-3. Soldering General Notes:
 - a. Recommend manual soldering to be used only for repair and rework purposes. The soldering iron should not exceed 30W in power. The tip of the soldering iron should not touch the reflector case to avoid heat-damage.
 - b. Maintain the pre-heat and peak temperatures with dip units as low as possible and the times as short as is feasible, since the products are susceptible to heat during flow soldering.
 - c. After soldering, least three minutes for the component to cool to room temperature before further operations.
 - d. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with for compatibility.